EP-600

Polymer Thick Film

Description

EP-600 two-part, silver-filled conductive epoxy is designed for component attachment, termination and other applications in hybrid circuits, membrane keypads and other electromechanical assemblies. EP-600 exhibits quick break-off after dispensing and will not cause shorts from stringing in high-speed automated production processes.

Key Features

- Low Temperature Cure
- Thixotropic properties, low viscosity & non-stringing characteristics make it ideal for high-speed dot-dispense processes which can run up to 70% faster
- Exhibits outstanding adhesion to most metal & plastic substrates
- Excellent temperature resistance & toughness allows for differences in coefficients of thermal expansion between bonded substrates
- Lateral component push-off testing on print-treated mylar substrates show EP-600 to have 30 to 40% greater bond strength than other conductive epoxy adhesives
- Convenient mix ratios and packaging are available. Options include 5-gram pre-weighed & sealed plastic CC-Packs and multiple bulk package configurations.

Typical Properties	
Viscosity	10-30 kcps. Brookfield DV-III Ultra, 25°C SC4-14 spindle @ SR 10
Solids	1
Metal	Ag
Color	A side: Silver / B side: Amber liquid
	<50 µ

Recommended Processing Guide	
Recommended Thinner	Do not thin

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Warranty

6 months

Storage

Store at ambient conditions away from direct light in aluminum package.